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INTERNATIONAL STANDARD



Field device integration (FDI®) - Standards
Part 5: FDI Information Model
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IEC 62769-5:2023

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI®) -

Part 5: FDI® Information Model

FOREWORD

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IEC 62769-5 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) added INTERACTIVE_TRANSFER_TO_DEVICE ACTION.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/858/CDV	65E/915/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device* integration (FDI^{\otimes}), can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

The IEC 62769 series has the general title Field Device Integration (FDI) and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles Generic Protocol Extensions
- Part 101-1: Profiles Foundation Fieldbus H1
- Part 101-2: Profiles Foundation Fieldbus HSE
- Part 103-1: Profiles PROFIBUS
- Part 103-4: Profiles PROFINET
- Part 109-1: Profiles HART and WirelessHART
- Part 115-2: Profiles Protocol-specific Definitions for Modbus RTU

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FIELD DEVICE INTEGRATION (FDI®) -

Part 5: FDI® Information Model

1 Scope

This part of IEC 62769 defines the FDI®1 Information Model. One of the main tasks of the Information Model is to reflect the topology of the automation system. Therefore, it represents the devices of the automation system as well as the connecting communication networks including their properties, relationships, and the operations that can be performed on them. The types in the AddressSpace of the FDI® Server constitute—a some kind of catalogue, which is built from FDI® Packages.

The fundamental types for the FDI® Information Model are well defined in OPC UA for Devices (IEC 62541-100). The FDI® Information Model specifies extensions for a few special cases and otherwise explains how these types are used and how the contents are built from elements of DevicePackages.

The overall FDI® architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration.

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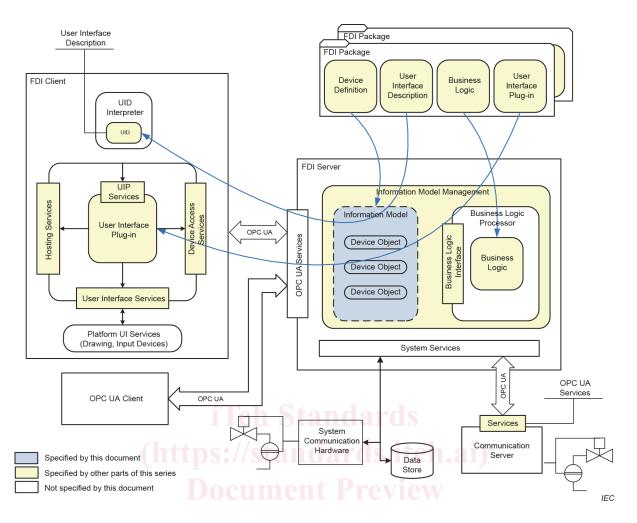


Figure 1 - FDI® architecture diagram

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2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, Industrial communication networks - Profiles - Part 1: Fieldbus profiles

IEC 61784-1-3:2023, Industrial networks – Profiles – Part 1-3: Fieldbus profiles – Communication Profile Family 3

IEC 61804-3, Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics

IEC 61804-4, Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 4: EDD interpretation

IEC 62541-3, OPC Unified Architecture – Part 3: Address Space Model

IEC 62541-4, OPC Unified Architecture – Part 4: Services

IEC 62541-5, OPC Unified Architecture – Part 5: Information Model

IEC 62541-6, OPC Unified Architecture – Part 6: Mappings

IEC 62541-8, OPC Unified Architecture – Part 8: Data Access

IEC 62541-100, OPC Unified Architecture - Part 100: OPC UA for Devices Device Interface

IEC 62769-1, Field Device Integration (FDI®) – Part 1: Overview

IEC 62769-2, Field Device Integration (FDI®) - Part 2: FDI-Client

IEC 62769-3, Field Device Integration (FDI®) – Part 3: Server

IEC 62769-4, Field Device Integration (FDI®) – Part 4: FDI® Packages

IEC 62769-6, Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings

IEC 62769-7, Field Device Integration (FDI®) - Part 7: FDI-Communication Devices

IEC 62769-1xx (all parts), Field Device Integration (FDI®) - Part 1xx-y: Profiles

OPC 10000-19, OPC Unified Architecture - Part 19: Dictionary Reference

3 Terms, definitions, abbreviated terms, acronyms and conventions

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1 and IEC 62769-3 apply.

ISO and IEC maintain terminology databases for use in standardization at the following addresses: iteh a/catalog/standards/iec/745111ce-3bdb-4Be-9115-e7409dd8b2d9/iec-62769-5-2

- IEC Electropedia: available at https://www.electropedia.org/
- ISO Online browsing platform: available at https://www.iso.org/obp

3.2 Abbreviated terms and acronyms

For the purposes of this document, the abbreviated terms and acronyms given in IEC 62769-1 and the following apply.

HMI Human Machine Interface

SCADA Supervisory Control and Data Acquisition

TCP Transmission Control Protocol

3.3 Conventions

For the purposes of this document, the conventions given in IEC 62769-1 apply.

3.3.1 Capitalization

Capitalization of the first letter of words is used in the IEC 62769 series to emphasize an FDI® defined term.